

CHO-FLEX® Conductive Coating and Ink



• **CHO-FLEX 601** coating is specifically designed for EMI shielding of copper/Kapton[†] flexible circuit laminates and for printing circuits on Kapton film. Upon cure, this coating exhibits excellent adhesion and flexibility, thermal stability, high conductivity and superior peel strength. It can be sprayed or silkscreened, and will withstand wave solder temperatures above 500°F (260°C) without losing any of its exceptional properties.

[†] Trademark of DuPont Company

• **CHO-FLEX 4430** polyester ink was developed for the membrane keyboard and sensor industries. It bonds to Mylar[†] films, and can be creased, heat-formed or scratched without affecting its performance. Pure silver-filled CHO-FLEX 4430 ink offers surface resistivity of 0.050 ohm/square at 0.0005 inch (0.013 mm) thickness.

Table 7 Ordering Information

| PRODUCT | ORDERING PART NUMBER | UNIT/ SIZE |
|---------------|----------------------|------------------|
| CHO-FLEX 601 | 52-01-0601-0000 | 1 pound (0.5 kg) |
| CHO-FLEX 4430 | 55-01-4430-0000 | 1 pound (0.5 kg) |

Note: Custom packaging can be accommodated. Please inquire.

Every shipment of Chomerics' conductive compounds is accompanied by a *Certificate of Conformance* to Chomerics specifications. Additional test reports can be obtained for a service charge. Quality control procedures conform to MIL-I-45208.

Table 8 Ordering Information

| SPECIFICATIONS AND PRODUCT CHARACTERISTICS (Contact Chomerics for complete specifications and test procedures) | | |
|---|-----------------------------|----------------------------|
| CHO-FLEX Coating or Ink | 601 | 4430 |
| Binder | polyurethane | polyester |
| Filler | Ag | Ag |
| Consistency | Thixotropic paste | Thixotropic paste |
| Typical Density | 1.67 | 3.80 |
| Maximum Surface Resistance, ohm/sq. | 0.06 | 0.08 |
| Use Temperature | -65 to 225°F (-54 to 107°C) | -65 to 185°F (-54 to 85°C) |
| Cure Cycle | 1.5 hrs. @ 360°F (182°C)* | 0.5 hr. @ 250°F (121°C) |
| Shelf Life, mos. | 6 | 9 |
| Coverage, in ² /lb. (m ² /kg)** | 4320 (6.13) | 3000 (4.26) |
| VOC, g/liter | 709 | 684 |

* Flexible circuit cure cycle: 4-5 min. @ 325°F (163°C) initial cure; 90 min. @ 360°F (182°C), 400 (2.76 PMPa) psi press cycle; 3-4 sec. @ 500°F (260°C) wave solder.

** Theoretical coverage. Actual coverage will be 50-100% of this value, depending on part geometry, operator skill, etc.